

In a surface acoustic wave (SAW) apparatus, a substrate having a SAW device provided with a balun function mounted thereon is provided on a multi-layered bottom portion of a package. Electrical wiring patterns are disposed between an upper layer and a lower layer of the bottom portion such that a delay line, a reactance component, or a resistance component is added to at least one of the balanced signal terminals. Balanced signal external terminals to connect the SAW device to an external device are disposed symmetrically with respect to the center of the package.